

KLEIBERIT 314.3

Single component D4 industrial glue for water resistant bonding in accordance to DIN/EN204.

Fields of application

- Bonding of windows and doors
- Surface bonding of partitions and parts
- Stair building
- Bonding of tenon and finger-joints
- Bonding of hard and exotic timbers
- Bonding of HPL sheets

Advantages

- Single component glue - no mixing necessary
- Suitable for hot- cold- and high frequency bonding
- Short press times with heat input
- No joint markings

Properties of the bond

- KLEIBERIT 314.3 tested in accordance to DIN/EN 204 conforming to D4
- KLEIBERIT 314.3 tested according to WATT 91
- Transparent and tool preserving glue line

Properties of the glue

Base:	PVAC dispersion
Specific gravity:	approx. 1.11 g/cm ³
pH-value:	approx. 3.0
Colour:	white, dries transparent
Consistency:	medium viscosity
Viscosity at 20°C	
Brookfield RVT spindle 4/20 rpm:	8,000 mPa s + 2,500 mPa s
Open time (at 20°C):	4-7 minutes
Chalk point:	approx. +10°C
Identification:	see our safety data sheet

Application methods

- Brush, spatula or glue roller
- Gluing devices fitted to frame presses and dovetailing machines
- Glue spreaders

Application tools must be made from stainless steel (V2A) or plastic

Application techniques

The materials to be glued must be free from dust, oil and grease and be acclimatised. The best working temperature is between 18-20°C, the best moisture content of the wood between 8-10%, inner areas and 10-14% window manufacture. Do not process below +15°C!

The adhesive must not come into contact with iron due to the danger of discoloration.

Generally single-sided glue application is sufficient. Double-sided application is recommended for hard and exotic timbers!

Application techniques

Application quantity:

150 g/m² when applied manually
 100 g/m² when applied via a machine
 both depending on substrate.

Open time: 4 - 7 min.

The open time depends on the application quantity, the absorption properties of the substrate, the moisture content of the wood and humidity and the temperature.

KLEIBERIT 314.3

Pressure:

0.2 - 0.4 N/mm² for surface bonding
 0.7 - 1.0 N/mm² for laminating and chip board bonding.

Press times:

Application	Temp.	Press time
Joint bonding	20°C	from 15 minutes
Surface bonding (HPL boards)	20°C	from 20 minutes
Surface bonding (HPL-Platten)	50°C	approx. 5 minutes
Surface bonding	80°C	approx. 2 minutes

Please note that any bonds made with KLEIBERIT 314.3 and the bonded substrate itself may only be exposed to high mechanical loading after a period of 30 minutes to 1 hour.

The final bond strength according to the stressing groups according to DIN EN 204 will be achieved after approximately 7 days.

Wood and wood based materials are natural products, which can, depending on the growing area, and through wood specific properties show discoloration.

Cleaning

Application devices and machines can be cleaned with water.

Packaging

plastic pail, 4.5 kg net
 plastic canister, 5.0 kg
 plastic pail, 10.0 kg net
 plastic pail, 28.0 kg net
 one-way drum, 130.0 kg net
 one way plastic container, 1,150.0 kg net

Additional packaging sizes available upon request.

Storage

Store in a cool place protected from frost and direct sunlight!

The recommended storage temperature in factory sealed containers is 10-25°C.

Higher temperatures reduce storage stability:

Temperature	Storage time
15°C	approx. 8 Months
20°C	approx. 6 Months
25°C	approx. 4 Months
30°C	approx. 2 Months

Version 27.07.2023 Iz; replaces previous versions.

Adhesive and Waste Disposal

Waste Code 080410

Our containers are made of recyclable material. Well drained containers can be recycled.

Service

Our application department may be consulted at any time without obligation. The statements made herein are based on our experience gained to date. They are to be considered as information without obligation. Please test and establish for yourself the suitability of our products for your particular purposes. No liability exceeding the value of our product can be derived from the foregoing statements. This also applies to the technical consultancy service which is rendered free of charge and without obligation.